ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES®	PC. Bannockł	ourn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an	on of the su compasses	bstances w all lower	vithin the manufactu level materials for v	rer listed i which the n	tem. Note: nanufacture	if the item is an as or has engineering	sembly with low responsibility.	
	.1 IPC Web Site for Information on IPC-1752 Standard Form Dist				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Info					fg Informa	tion			
upplier Information														
Company name* Compan			mpany unique ID			Unique ID Authority				Respon	Response Date*			
nsemi							2			2024-04	2024-04-20			
Contact Name	ct Name Title - Contact]	Phone - Contact*				Email - Contact*				
roduct-Env-Stewards Product Enviro			ro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produc			roduct Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	М	anufacturing Site		Weight*	UOM	Unit Type	
	FAN23S	FAN23SV70AMPX 20A Buck Reg		julator		2024-04-20		PI	PBB		86.261	mg	Each	
Ianufacturing Proccess Informat	tion		·			•						·		
Terminal Plating / Grid Array Ma	terial 7	rial Terminal Base Allo		J-STD-020 MSL Rating		Peak Proce	ak Process Body Temperatu		ure Max Time at Peak Temp		ure Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	secon	ids 3			
omments														
vel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.062	mg	Supplier	Zinc (Zn)	7440-66-6		0.0049	mg
			Supplier	Iron (Fe)	7439-89-6		0.0955	mg
			Supplier	Copper (Cu)	7440-50-8		3.9604	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0012	mg
Die	1.14	mg	Supplier	Silicon (Si)	7440-21-3		1.14	mg
Die Attach Solder	1.568	mg	Supplier	Silver (Ag)	7440-22-4		0.0392	mg
			А	Lead (Pb)	7439-92-1	7a	1.4504	mg
			Supplier	Tin (Sn)	7440-31-5		0.0784	mg
Lead Frame	30.983	mg	Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.7281	mg
			Supplier	Copper (Cu)	7440-50-8		30.2084	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0093	mg
Mold Compound-Black	45.784	mg	Supplier	Carbon Black (C)	1333-86-4		0.2289	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.061	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		2.747	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.747	mg
Plating	1.78	mg	Supplier	Tin (Sn)	7440-31-5		1.78	mg
Wire Bond - Au	0.658	mg	Supplier	Gold (Au)	7440-57-5		0.658	mg
Wire Bond - Cu	0.286	mg	Supplier	Copper (Cu)	7440-50-8		0.286	mg